



Customer Information Notification

2020070201

Issue Date: 22-Jul-2020

Effective Date: 23-Jul-2020

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - Data Sheet Update (Corrections and Clarifications) | | | |

MC33771B Data Sheet Update to Rev 6.0 (Corrections and Technical Clarifications)

Description

NXP Semiconductors announces the data sheet update to revision 6.0 for the MC33771B Battery Cell Controller IC devices associated with this notification. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

Data Sheet Changes:

1. Section 2: Correct typos features description (typo correction)
2. Table 9: Update of max value for RPD (characteristics update)
3. Table 9: Update of min/max values for tWAVE_BIT_BITx and tWAVE_DC_ON (characteristics update)
4. Table 9 and Section 9.17: Add recommendations about CTn leakage (characteristics update)
5. Table 9, Footnote 14: Update safety margin value (informative)
6. Table 11: Reword to clarify communication behavior in Normal, Diagnostic, Idle and Sleep mode (description improvement)

7. Section 9.4.2, Section 12.1 and Tables 64, 65 and 66: Clarify note about Vana fault (description improvement)
8. Section 9.13: Add note regarding current sense in sleep mode and cyclic acquisition (additional recommendations)
9. Section 9.17: Clarify CBx_CFG bits behavior (description improvement)
10. Section 9.18: Add step in "Cell balance fault diagnostics" (procedure modification, already implemented in the Safety Manual)
11. Tables 39 and 40: Correct typos in bit numbers affected to each item (typo correction)
12. Section 11: Reformat register map (description improvement)
13. Section 11: Clarify status for reserved and not used bits (description improvement)
14. Table 92: Update list of "reserved" registers (informative)
15. Section 13.2.1: Add paragraph regarding CTREF variations (optional application improvement - optional diodes - no system impact)
16. Figure 37 and Table 97: Add optional recommendation if VPWR > 55 V during hotplug (application improvement - optional TVS diodes - no system impact)
17. Table 102: Correct CTPL value (EVB hardware change, no system impact)
18. Other minor typo corrections throughout the document

** Documentation change only for customer clarifications - absolutely no changes to the device / product **

New MC33771B rev 6.0 data sheet may be obtained from the secure DocStore portal:

<https://www.docstore.nxp.com/products?path=/content/docstore/product-hierarchy/Automotive-Battery-Management/MC33771--MC33772--MC33664/Datasheet&folderuuiid=10722735-c3a3-47dd-a794-8eec20db8c66>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheet has been updated to correct errors and provide additional technical clarification on some device features, as well as on the register map.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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